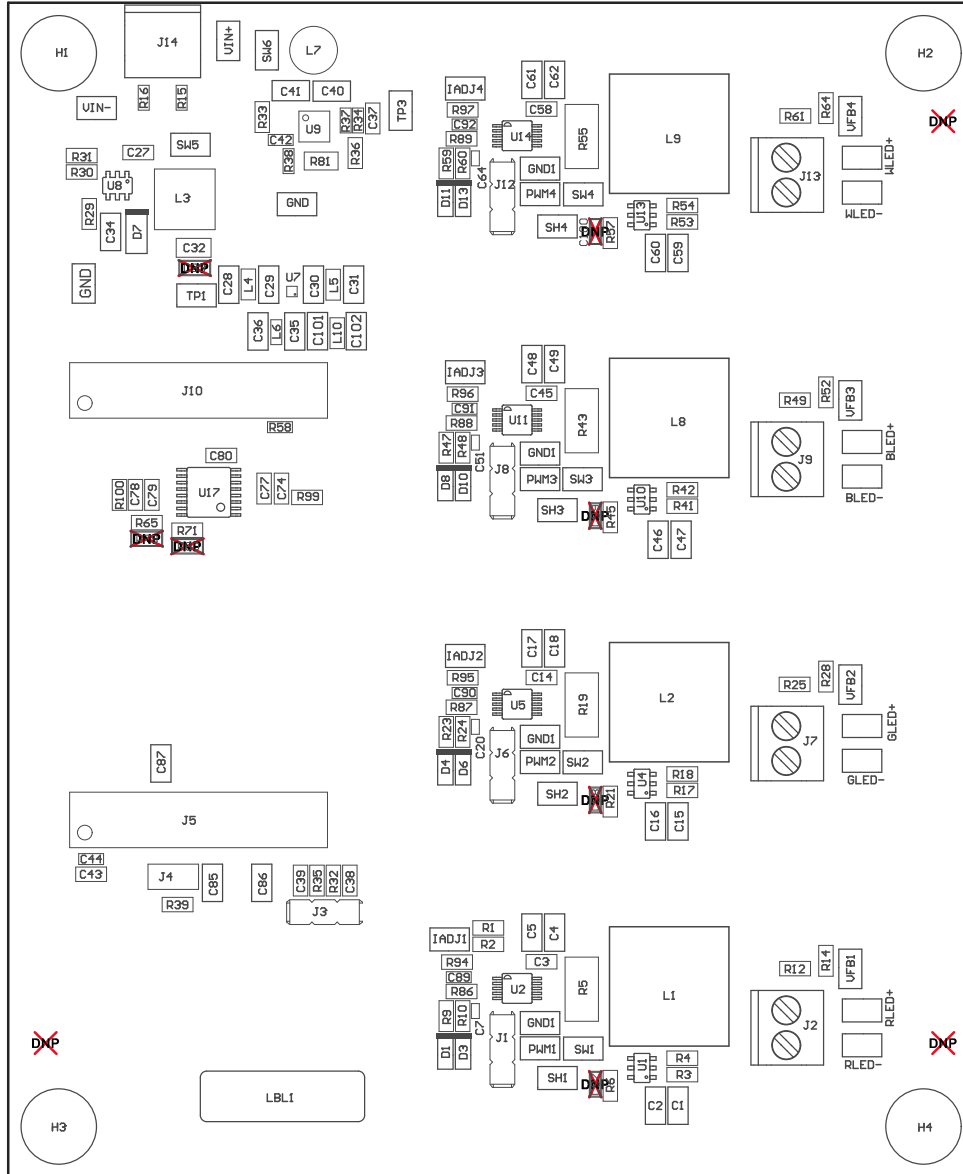


Z21 ■ Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per the Label Table in the PDF schematic.

Z22 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

Z23 ■ These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

Z24 ■ These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

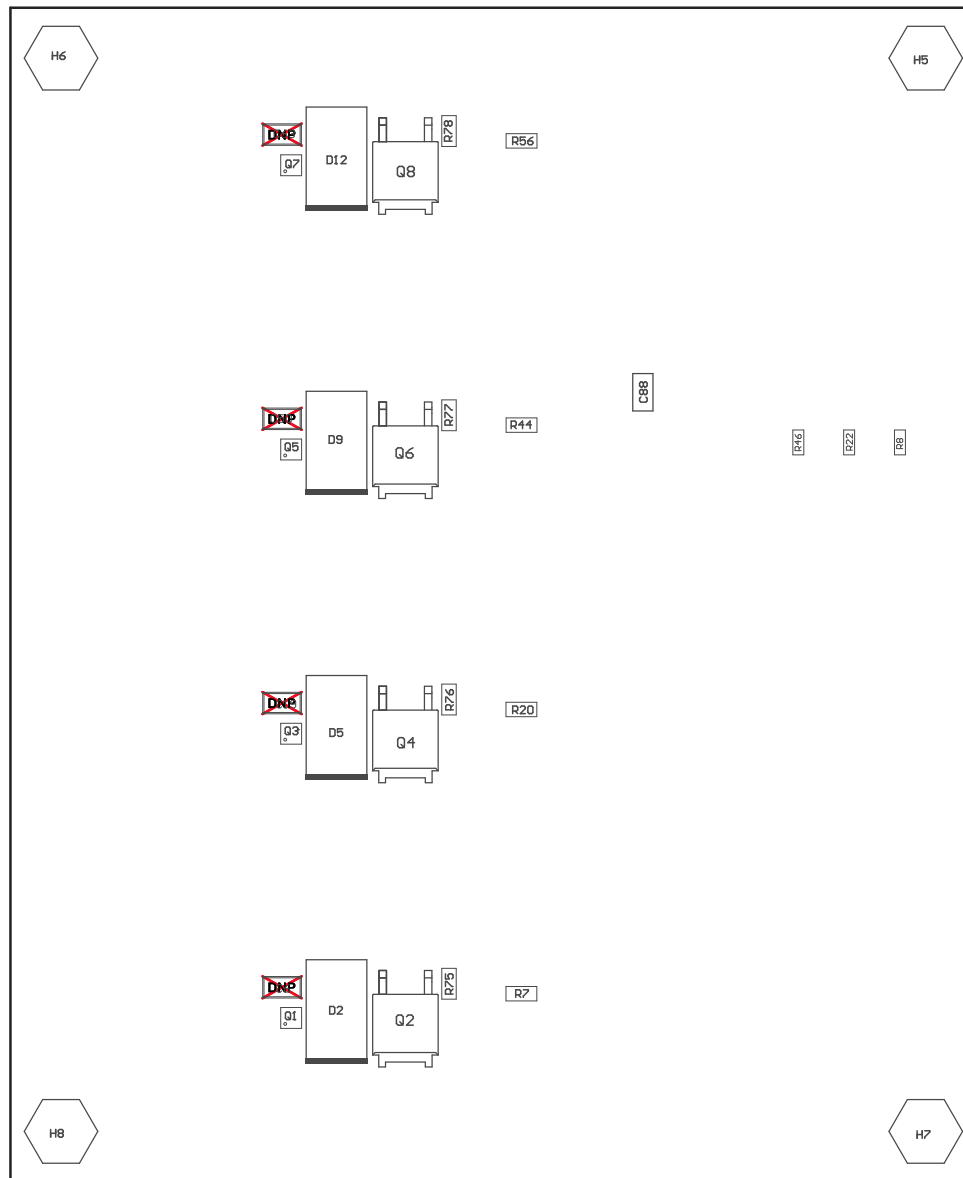


COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT:

001

PCB VIEWED FROM TOP SIDE	BOARD #:	TIDA-01415	REV:	E1	SUN REV:	Not In VersionControl
M5 Assembly Top		TID #:	TIDA-01415			
PLOT NAME =	Top Assembly Drawing	GENERATED :	4/26/2017	2:39:26 PM	TEXAS INSTRUMENTS	



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED.

ASSEMBLY VARIANT: 001

PCB VIEWED FROM BOTTOM SIDE	BOARD #: TIDA-01415	REV: E1	SUN REV: Not In VersionControl
M6 Assembly Bottom	TID #: TIDA-01415		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/26/2017	2:39:28 PM	TEXAS INSTRUMENTS

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